

# PVモジュール信頼性評価：加速試験中評価手法の開発

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## Introduction & Procedures

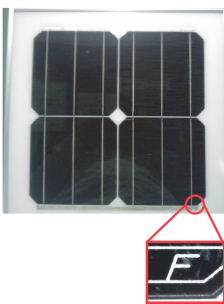
**Motivation & Background**

Our Task: Thin Wafer PV Cells + Ribbon with Opt. Properties  
-> Reliable / Durable Interconnected PV Modules

To Confirm the Reliability of Interconnection on these New Designed PV Modules,

- Higher Stress than Conventional Thermal Cycling  
-40 °C/85 °C → -60 °C/100 °C  
Thermal Cycling → Rapid Thermal Cycling  
200 cycles → 3,000 cycles +
- *in situ* Detection of Failures during Testing  
*in situ* AC Impedance Spectroscopy

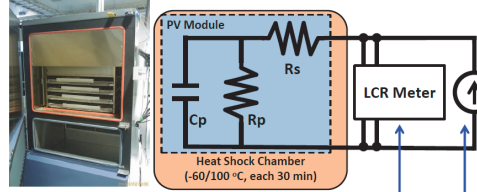
Thin Wafer PV Cells / Light Weight Glass → "FREAA PV Module"



**Tested PV Mini-Module**

- Thin Wafer PV Cells  
Mfg. in FREAA Lab.  
100 μm Thickness  
n-type c-Si / p-doped
- Chemical Strengthened Glass  
0.8 mm Thickness
- Interconnection  
Cu-Ribbon (1.3 mm)  
by Soldering  
with J-Box & Cables

**Experimental Setup & AC Equivalent Circuit of PV Module**

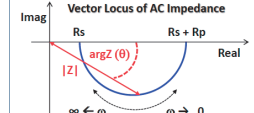


Heat Shock Chamber (-60/100 °C, each 30 min)

LCR Meter

KEYSIGHT E4980A (LCR Meter)  
KEYSIGHT 42841A (Bias Current Source)

Vector Locus of AC Impedance



$|Z|$ : Impedance (abs) in AC Eq. Circuit  
 $argZ$ : Argument Z

## Summary

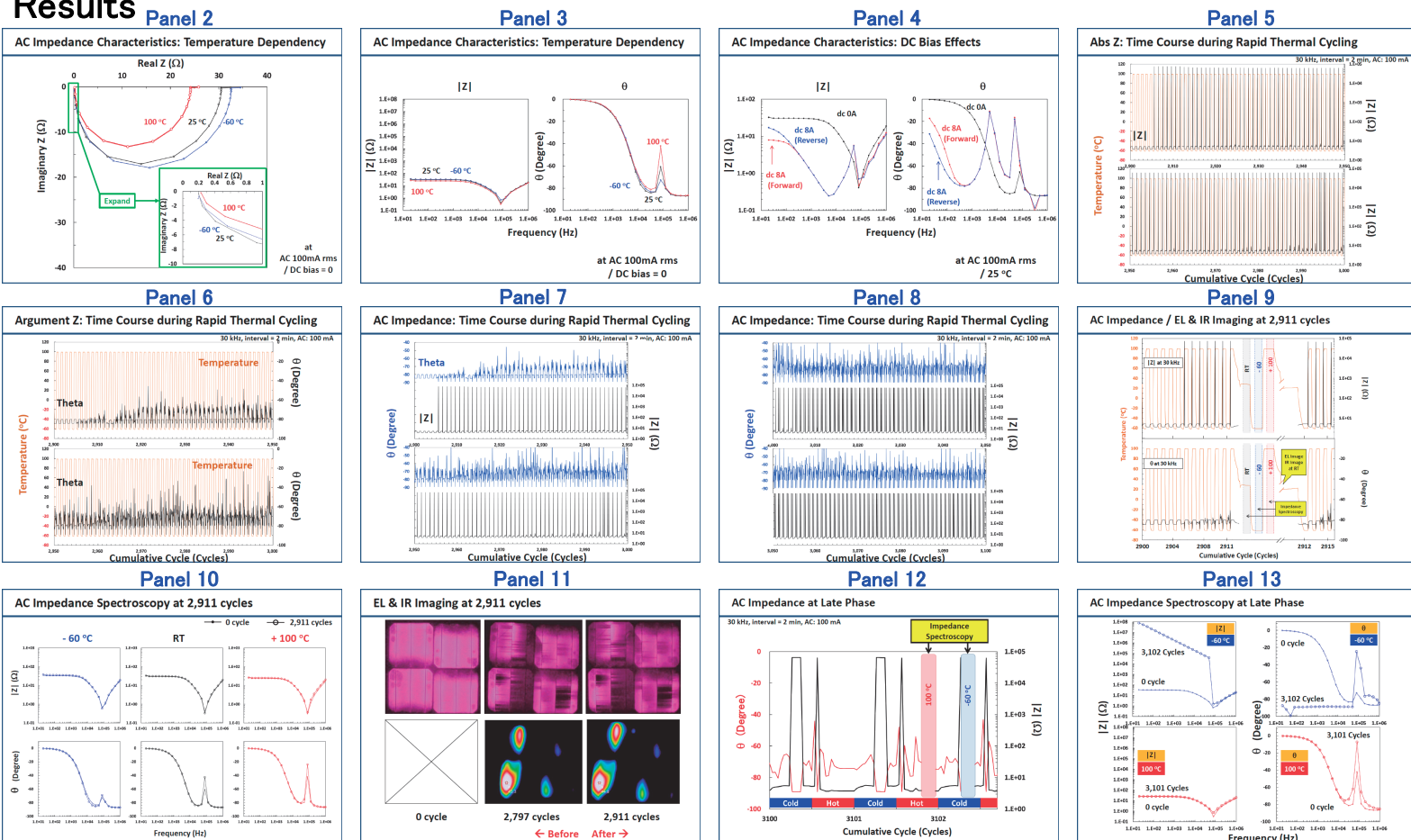
We previously reported that the "spike-like" elevation of whole impedance was observed, which was calculated by the measurement of  $I_{AC}$  and  $V_{AC}$ , prior to the occurrence of interconnection failure during Rapid Thermal Cycling (RTC) test (JJAP 51: 10NF13, 2012). In this study, the AC impedance parameters ( $|Z|$  and  $\theta$ ) were continuously measured during this testing.

Then, we obtained the results as follows;

- The logarithmical impedance-elevation identified by  $|Z|$  elevation was observed at ca. 3,000 cycles of RTC (**Panel 1**). Interestingly, the increasing of  $|Z|$  consistently accompanied with  $\theta$  decreasing.
- These level-changes of  $|Z|$  and  $\theta$  were observed in the temperature elevation phase, and also in the low temperature phase after the PV modules were sufficiently adapted at low temperature (**Panel 5-8**).
- When the PV module was completely adapted to any temperature just after these phenomena were happened, the level-changes of AC parameters were not detected at all (**Panel 9-10**). Simultaneously, any alterations of EL and IR images were not confirmed at room temperature (**Panel 11**).
- From the AC impedance spectroscopy (20 Hz ~ 50 kHz) during the  $|Z|$  elevating period (at -60 °C), it is revealed that the levels of  $|Z|$  and  $\theta$  were  $>10^4 \Omega$  and almost -90°, respectively (**Panel 12-13**).

These results suggest that the soldering failure in PV modules (including the disconnection in junction box) can be observed when the RTC testing was conducted for prolonged cycles (ca. 3,000 cycles), and that this failure can be detected only during the RTC testing, as a complete detachment between electrical junctions, by the continuous *in situ* AC impedance measurement.

## Results



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